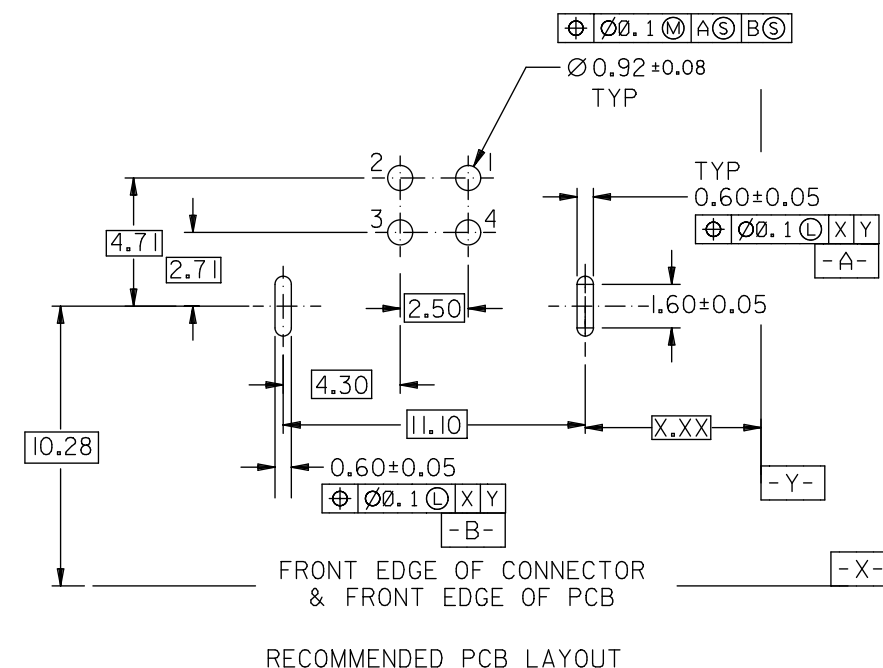
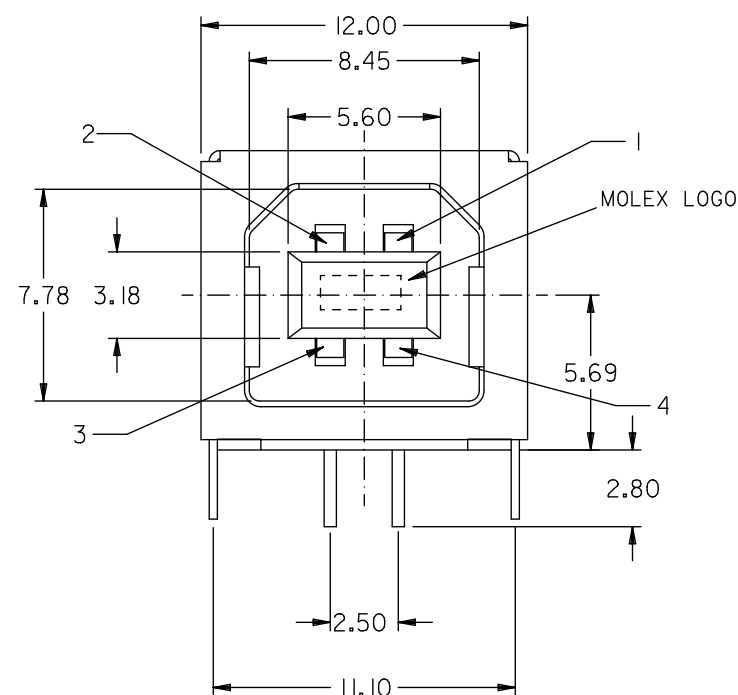
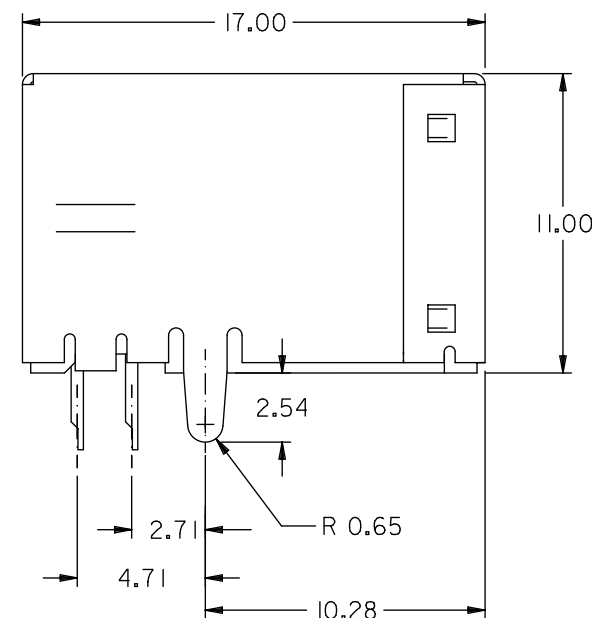
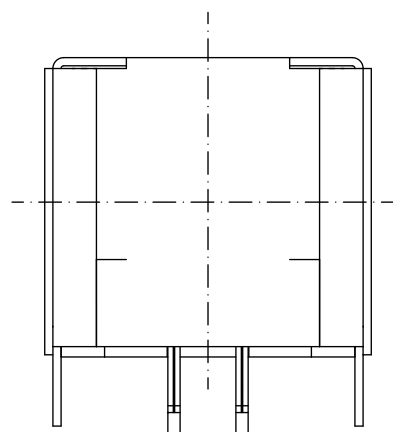
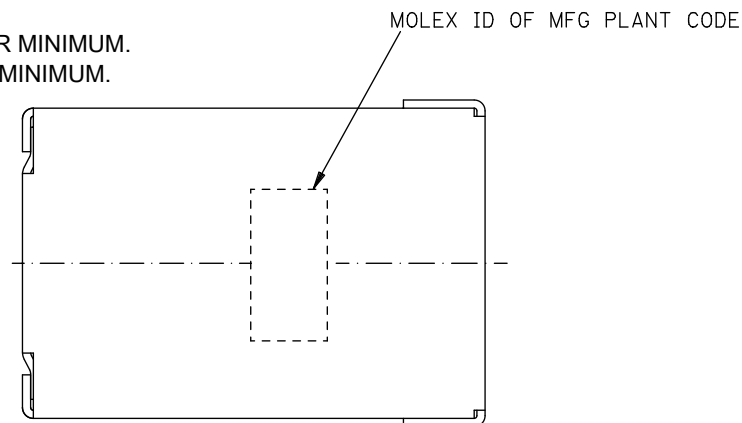
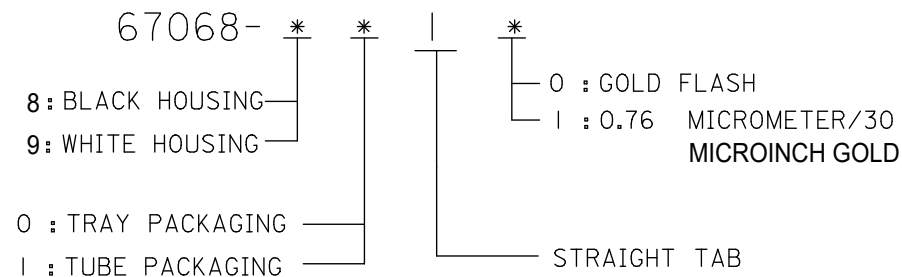


NOTES:

- MATERIAL:
 - HOUSING:
 - (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL 9 V-0, COLOR: BLACK.
 - (b) POLYESTER, GLASS FIBER FILLED, UL 94 V-0, COLOR: WHITE.
 - TERMINAL: PHOSPHOR BRONZE
 - METAL SHEEL: COPPER ALLOY
- PLATING:
 - TERMINAL:
 - (c) GOLD FLASH.
 - (d) GOLD (Au). THICKNESS = 30 MICROINCH MINIMUM. / 0.76 MICROMETER MINIMUM.
 - SOLDER TAIL: PURE TIN (Sn) THICKNESS = 75 MICROINCH MINIMUM. / 1.9 MICROMETER MINIMUM.
 - UNDER PLATE: NICKEL (Ni), THICKNESS = 50 MICROINCH MINIMUM. / 1.27 MICROMETER MINIMUM.
 - METAL SHELL:
 - PLATING: OVERALL PLATE: NICKEL (Ni), ALL OVER SURFACE. THICKNESS: 50 MICROINCH MINIMUM. / 1.27 MICROMETER MINIMUM.
- DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
RECOMMENDED PCB THICKNESS: 1.60 ± 0.05.
- PRODUCT SPECIFICATION: REFER TO PS-67998-0000.



PART NUMBER LEGEND:

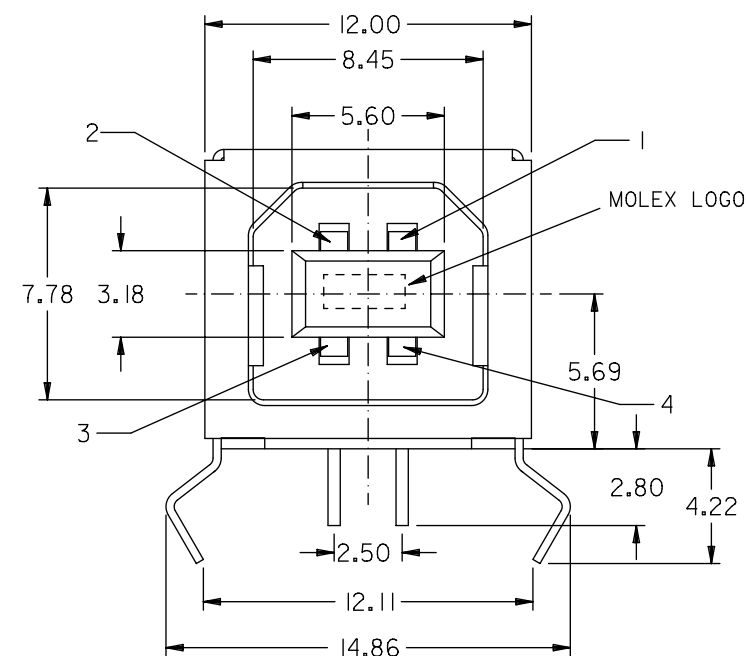
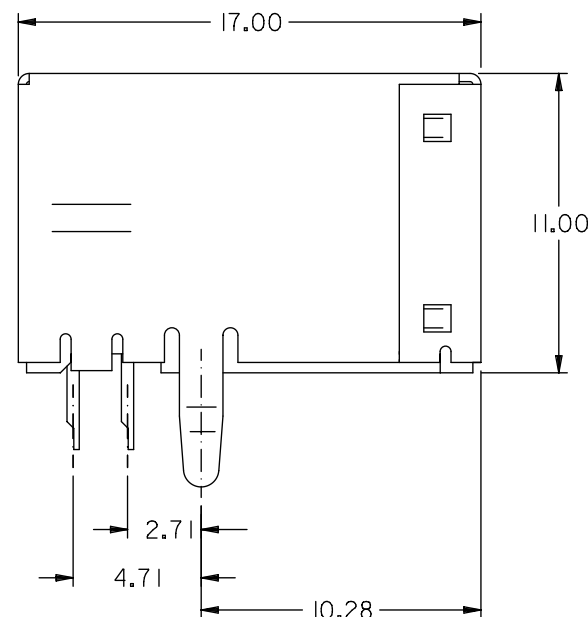
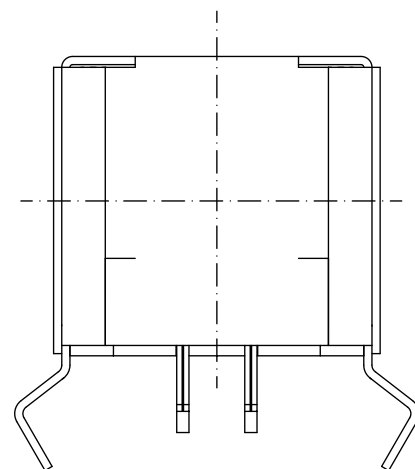
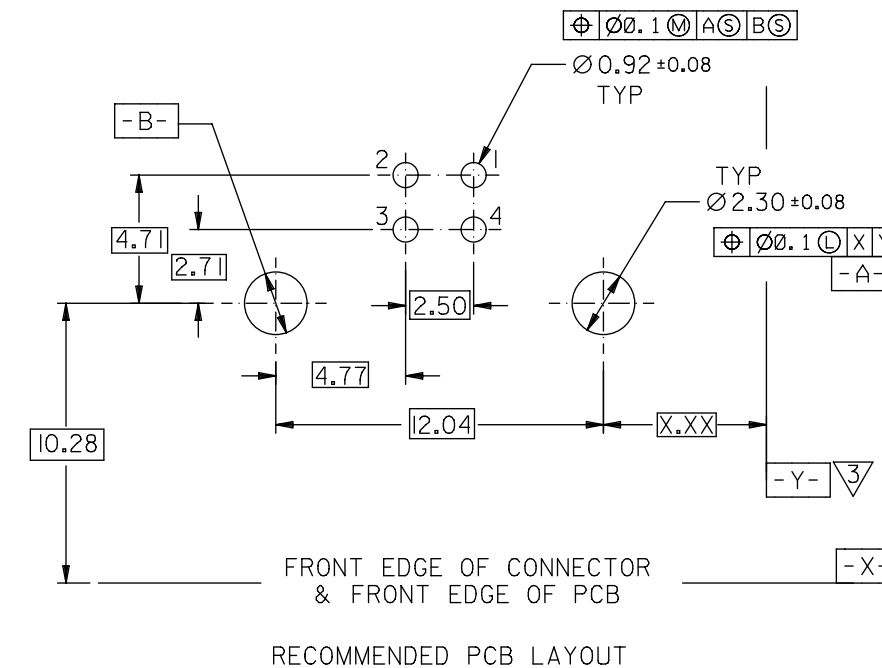
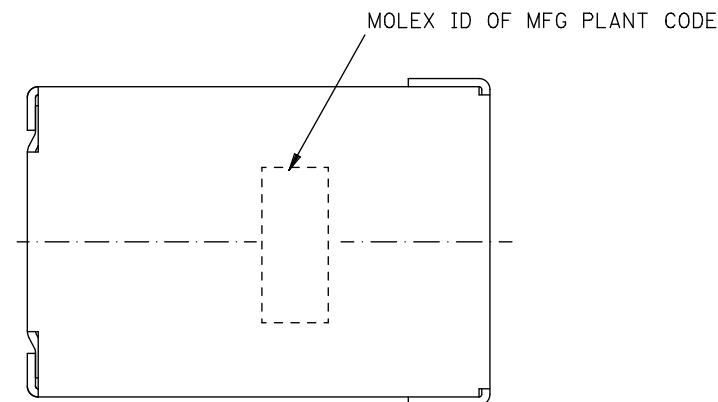


| | HOUSING COLOR | PLATING |
|------------|---------------|----------------------|
| 67068-8010 | (a) BLACK | (c) GOLD FLASH |
| 67068-8011 | (a) BLACK | (d) 30MICROINCH GOLD |
| 67068-9011 | (b) WHITE | (d) 30MICROINCH GOLD |

| | | | | | | | | | | |
|---|---------------------------------------|----------------|---|--|------------------------|-----------------|---------------|-----------------|--------------------------|----------------------|
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | | | | |
| FUNCTIONAL SYMBOLS | DIMENSION UNITS | SCALE | CURRENT REV DESC: | | | | | | | |
| $\nabla = 0$ | mm | 1:1 | EC NO: 802815 DRWN: KCHENG06 2024/09/02 CHKD: HORACM1 2024/10/31 APPR: HORACM1 2024/10/31 INITIAL REVISION: DRWN: DHU 2004/11/24 APPR: YTYAP 2004/11/25 | | | | | | | |
| $\nabla = 0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | | | | | | | | |
| $\nabla = 0$ | ANGULAR TOL ± 3.0° | | | | | | | | | |
| DIVISIONAL SYMBOLS | 4 PLACES ± | 3 PLACES ± | | | | | | | | |
| | 2 PLACES ± 0.25 | 1 PLACE ± 0.25 | PRODUCT CUSTOMER DRAWING DOCUMENT NUMBER: SD-67068-003 DOC TYPE: PSD DOC PART: 001 REVISION: B | | | | | | | |
| | 0 PLACES ± | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIRD ANGLE PROJECTION | DRAWING: B-SIZE | SERIES: 67068 | MATERIAL NUMBER | CUSTOMER: GENERAL MARKET | SHEET NUMBER: 2 OF 3 |

NOTES:

1. MATERIAL:
 - HOUSING:
 - (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL 9 V-0, COLOR: BLACK.
 - (b) POLYESTER, GLASS FIBER FILLED, UL 94 V-0, COLOR: WHITE.
 - TERMINAL: PHOSPHOR BRONZE
 - METAL SHEEL: COPPER ALLOY
2. PLATING:
 - TERMINAL:
 - CONTACT AREA:
 - (c) GOLD FLASH.
 - (d) GOLD (Au). THICKNESS = 30 MICROINCH MINIMUM. / 0.76 MICROMETER MINIMUM.
 - SOLDER TAIL: PURE TIN (Sn) THICKNESS = 75 MICROINCH MINIMUM. / 1.9 MICROMETER MINIMUM.
 - UNDER PLATE: NICKEL (Ni), THICKNESS = 50 MICROINCH MINIMUM. / 1.27 MICROMETER MINIMUM.
 - METAL SHELL:
 - PLATING: OVERALL PLATE: NICKEL (Ni), ALL OVER SURFACE. THICKNESS: 50 MICROINCH MINIMUM. / 1.27 MICROMETER MINIMUM.
3. DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
RECOMMENDED PCB THICKNESS : 1.60±0.05.
4. PRODUCT SPECIFICATION : REFER TO PS-67998-0000.



| | | |
|------------|---------------|---------------------|
| | HOUSING COLOR | PLATING |
| 67068-7041 | (a)BLACK | (d)30MICROINCH GOLD |

| | | | | | | | | |
|--|---|--------------------------|--|-----------------------------------|---|--|--------|-----------------|
| FUNCTIONAL SYMBOLS | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | CURRENT REV DESC: | | molex | | | |
| | DIMENSION UNITS | SCALE | | | | | | |
| $\nabla = 0$ | mm | 1:1 | EC NO: 802815 DRWN: KCHENG06 CHKD: HORACM1 APPR: HORACM1 INITIAL REVISION: DRWN: DHU APPR: YTYAP | | USB B TYPE CONNECTOR KINK TYPE BOARDLOCK LEAD-FREE | | | |
| $\nabla = 0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | | | | | | |
| $\nabla = 0$ | ANGULAR TOL ± 3.0° | | | | | | | |
| DIVISIONAL SYMBOLS | 4 PLACES | ± | 2024/09/02 2024/10/31 2024/10/31 | | PRODUCT CUSTOMER DRAWING | | | |
| | 3 PLACES | ± | | | | | | |
| | 2 PLACES | ± 0.25 | | | DOCUMENT NUMBER SD-67068-003 | | | |
| | 1 PLACE | ± 0.25 | | | | | | DOC TYPE PSD |
| 0 PLACES | ± | 2004/11/24 2004/11/25 | | MATERIAL NUMBER GENERAL MARKET | | | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIRD ANGLE PROJECTION | DRAWING | SERIES | SHEET NUMBER | | 3 OF 3 | |
| | | | B-SIZE | 67068 | | | | |

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,
 (b) POLYESTER, GLASS FIBER FILLED, UL94V-0, COLOR: WHITE,
 TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

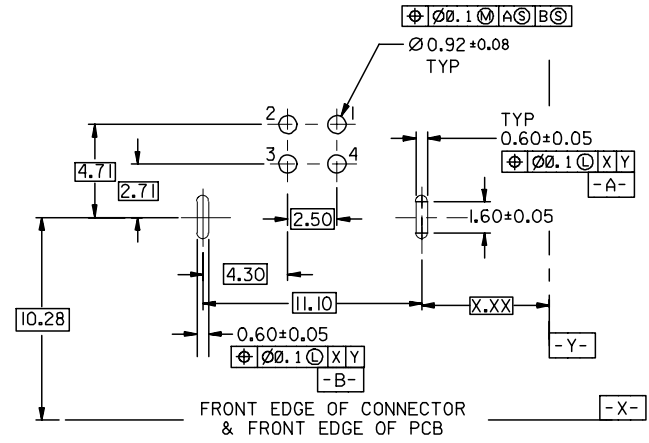
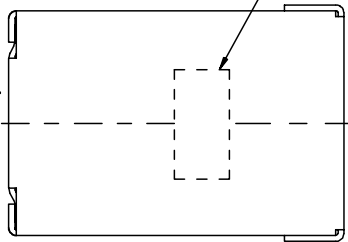
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

METAL SHELL :
 PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

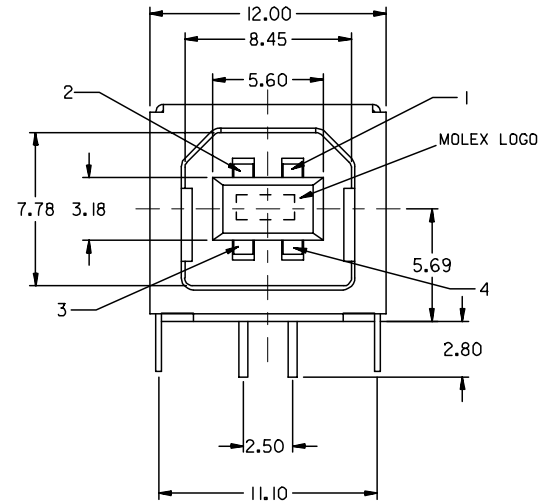
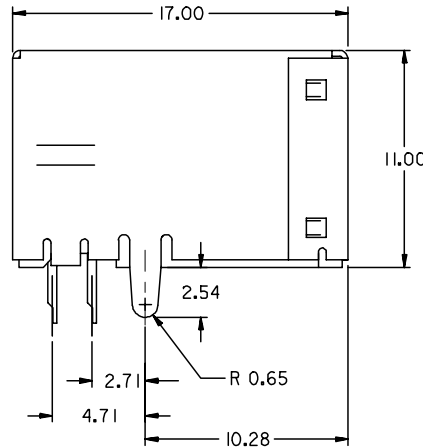
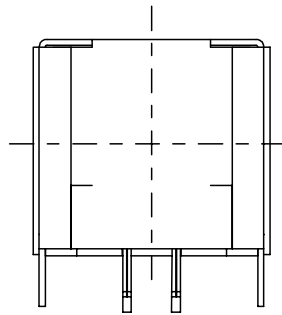
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05
 4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

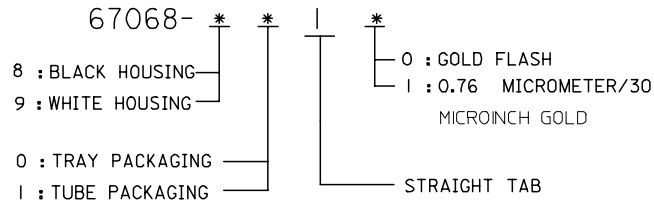
MOLEX ID OF MFG PLANT CODE



RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:



| | | | | | | | |
|--|--|--|--|--------------------------------|--|------------------------|----------------|
| NEW RELEASE EC NO: SH2005-0142 DRWN: DAVID HU 2004/11/05 CHKD: HARVEY 2004/11/25 APPR: TYAP 2004/11/25 | QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | DIMENSION STYLE MM ONLY | SCALE 4:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | ▽=0 ∇=0 | mm INCH | DRAWN BY DATE DAVID HU 2004/11/05 | TITLE | USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE) | | |
| | | 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 2004/11/05 1 PLACE ± 0.25 ± --- | CHECKED BY DATE 2004/11/05 | APPROVED BY DATE 2004/11/05 | MOLEX MOLEX INCORPORATED | | |
| | | ANGULAR ± 3 ° | MATERIAL NO. | DOCUMENT NO. | SD-67068-003 | | SHEET NO. 2 |
| | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | SEE NOTES | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |

9 8 7 6 5 4 3 2 1

8 7 6 5 4 3 2 1

NOTES :
 1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

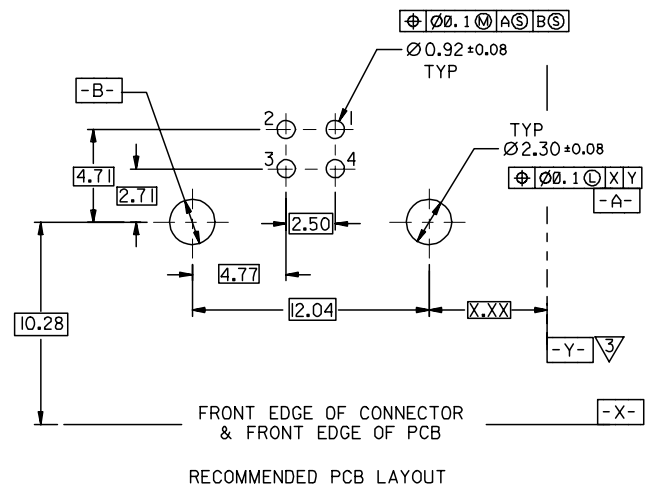
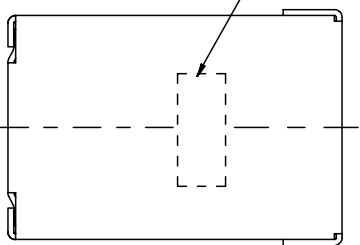
METAL SHELL :
 PURE TIN(SN), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

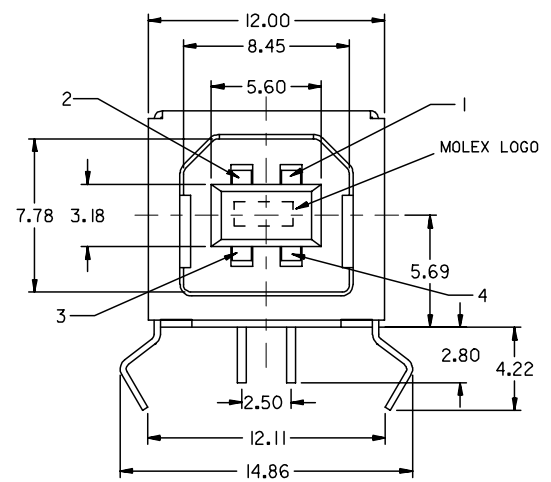
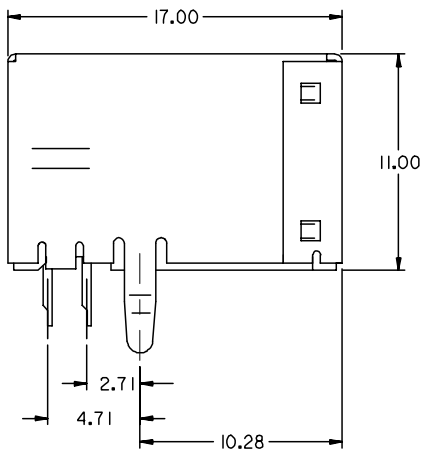
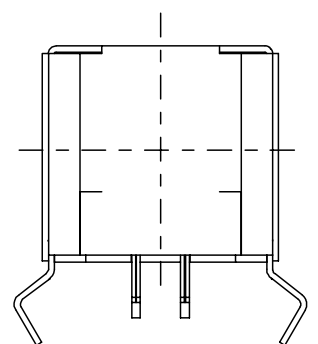
▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR
 & FRONT EDGE OF PCB
 RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:
 67068- 7041

ENG. NO.
 EDP NO.
 SIMILAR ITEM
 CAD FILE :
 DO NOT SCALE DRAWING

| | | | | | | |
|---|---------------------------|-----|----------|-------------------------|--------------------------------|---|
| | | | | MATERIAL : SEE NOTES | | MOLEX TAIWAN LTD. SHEET 3 OF 4 |
| | | | | FINISH : SEE NOTES | | |
| | | | | WIRE RANGE : | | GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010 |
| | | | | INS. RANGE : | | ENG. NO.: SD-67068-003 |
| A | NEW RELEASE FOR LEAD-FREE | | DAVID HU | 2004/11/5 | | REV A |
| LTR | REVISION RECORD | ECN | DR | DATE | DRAWN BY 2004/11/5 DAVID HU | CHK'D BY |
| REVISE ONLY ON CAD SYSTEM | | | | | APPR'D BY | SCALE 4 : 1 |
| TITLE : HIGH TEMP.USB B TYPE CONNECTOR KINK TYPE BOARD LOCK (LEAD-FREE) | | | | | | |

ENG. NO SDA-67068-****

EDP NO.

SIMILAR ITEM

CAD FILE : S6706802

DO NOT SCALE DRAWING

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH.
(b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

/1.27 MICROMETER MINIMUM.

METAL SHELL :

PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

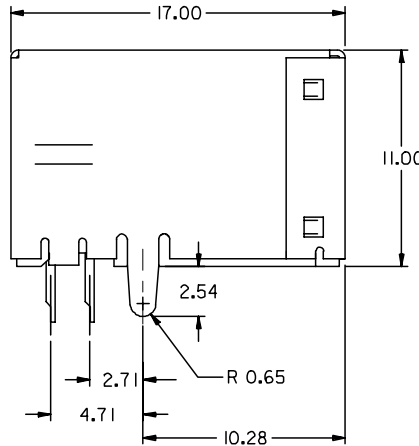
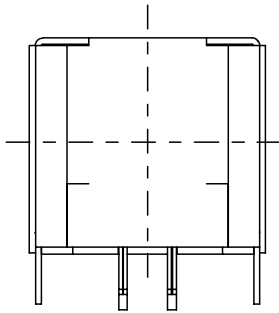
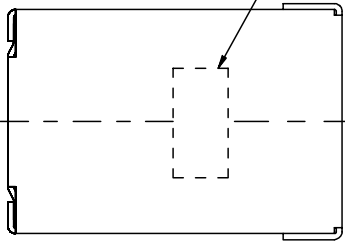
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

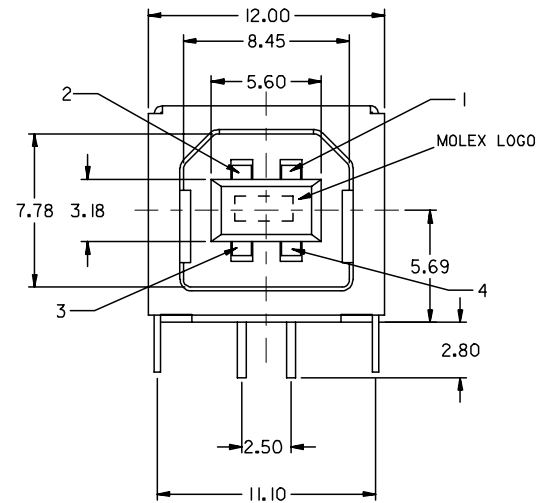
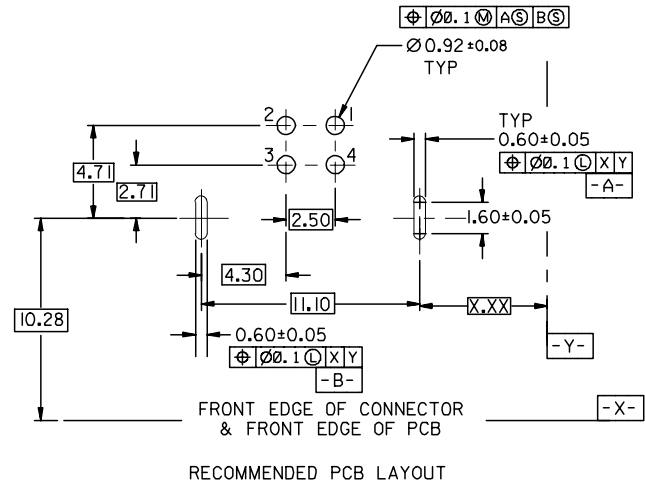
4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068- 7051



| | | | | | | |
|-----|---------------------------|----------|-----------|--------------------------------|----------|--|
| | | | | MATERIAL : SEE NOTES | | MOLEX TAIWAN LTD. SHEET 4 OF 4 |
| | | | | FINISH : SEE NOTES | | |
| | | | | WIRE RANGE : | | GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010 |
| | | | | INS. RANGE : | | ENG. NO.: SD-67068-003 |
| A | NEW RELEASE FOR LEAD-FREE | DAVID HU | 2004/11/5 | DRAWN BY 2004/11/5 DAVID HU | | REV A |
| LTR | REVISION RECORD | ECN | DR | DATE | CHK'D BY | TITLE : HIGH TEMP USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE) |
| | | | | APPR'D BY | | SCALE 4 : 1 |